Partial **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2940	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 20:54
L2	2342	257/737.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 20:55
L3	1	((conductive adj bump) and (semiconductor adj chip) and (surface with (bonding adj pad)) and (first adj metal) and (conductive adj paste) and (second adj metal) and (base adj portion) and (peripheral adj portion)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 20:57
S1	2	("6159837").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/25 15:52